
2SK1339

Silicon N-Channel MOS FET

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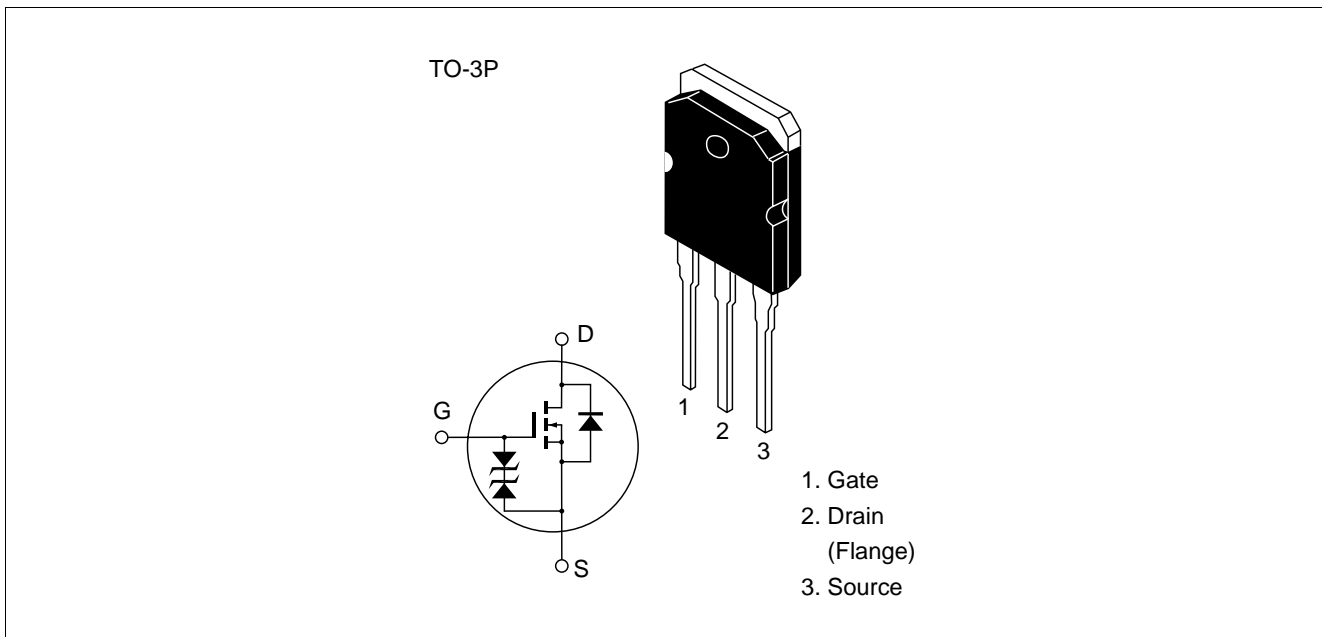
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline



2SK1339

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	900	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I_D	3	A
Drain peak current	$I_{D(pulse)}^{*1}$	7	A
Body to drain diode reverse drain current	I_{DR}	3	A
Channel dissipation	Pch^{*2}	80	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

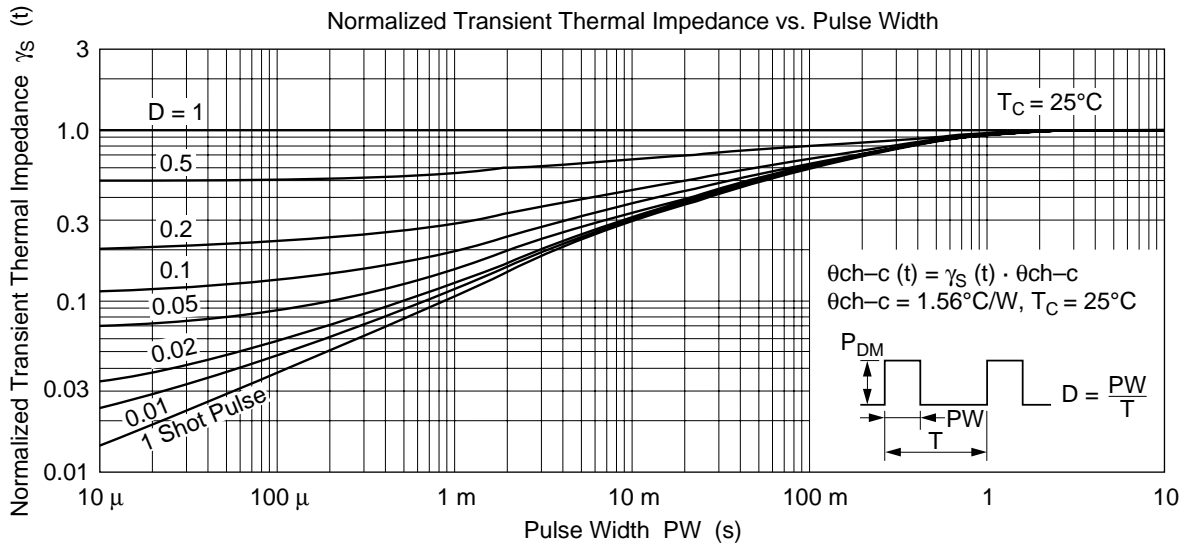
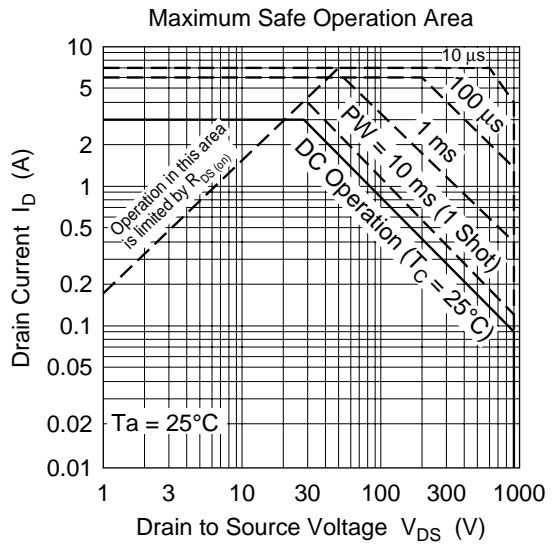
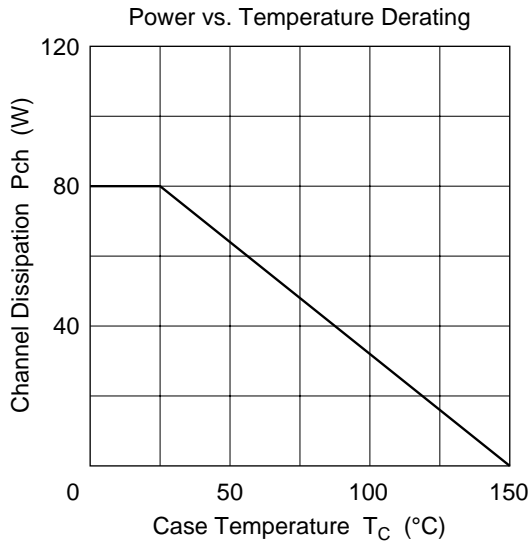
Notes: 1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$
2. Value at $T_c = 25^\circ C$

Electrical Characteristics (Ta = 25°C)

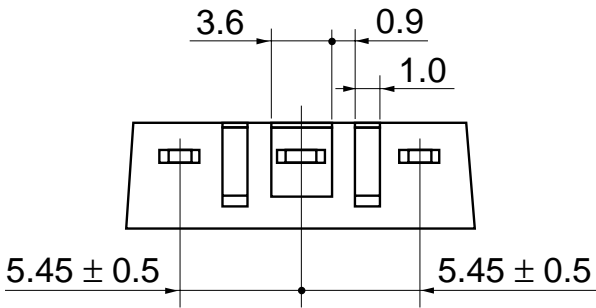
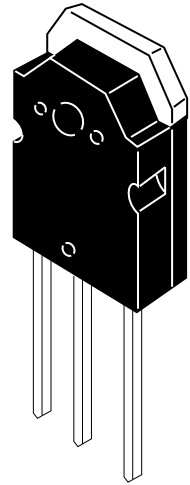
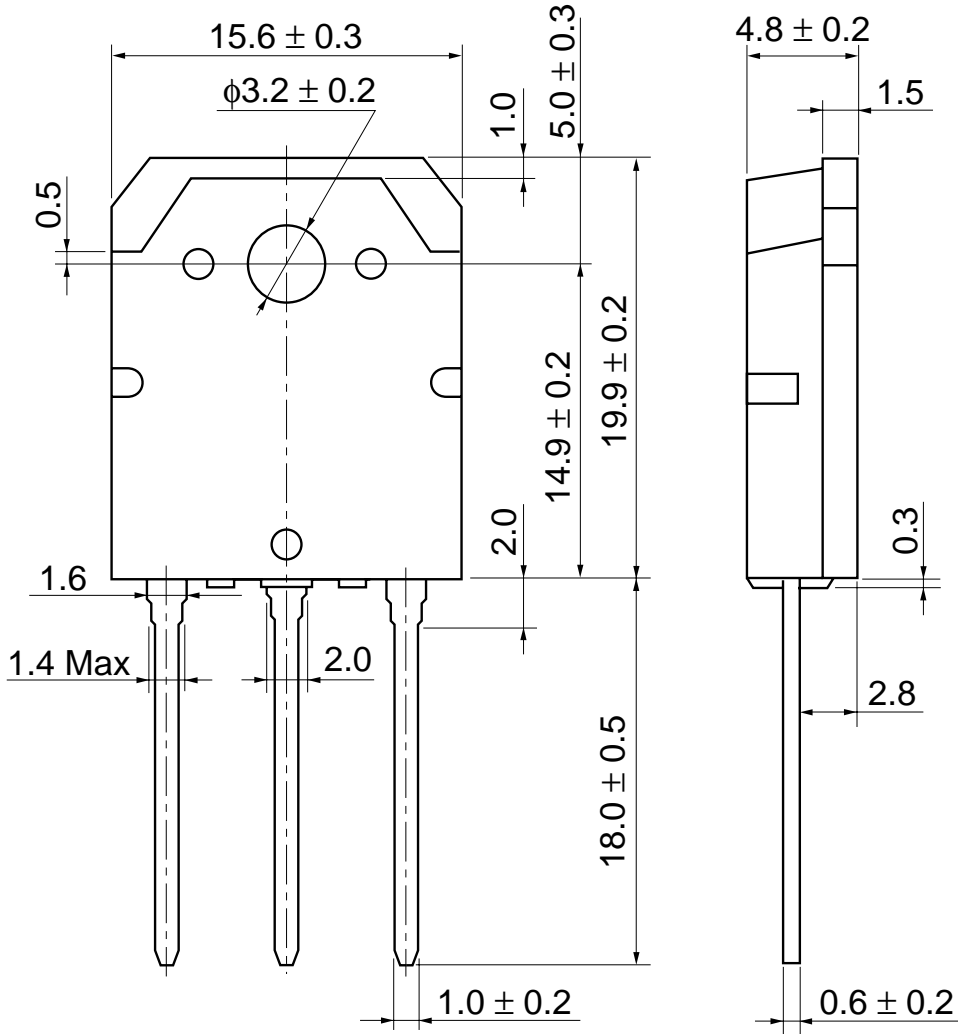
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	900	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 30	—	—	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	250	μA	$V_{DS} = 720 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	—	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	—	5.0	7.0	Ω	$I_D = 1.5 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	yfs	1.2	1.9	—	S	$I_D = 1.5 \text{ A}, V_{DS} = 20 \text{ V}^{*1}$
Input capacitance	C_{iss}	—	425	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	C_{oss}	—	175	—	pF	$f = 1 \text{ MHz}$
Reverse transfer capacitance	C_{rss}	—	85	—	pF	
Turn-on delay time	$t_{d(on)}$	—	10	—	ns	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t_r	—	40	—	ns	$R_L = 15 \Omega$
Turn-off delay time	$t_{d(off)}$	—	50	—	ns	
Fall time	t_f	—	55	—	ns	
Body to drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_F = 3 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t_{rr}	—	850	—	ns	$I_F = 3 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note: 1. Pulse test

See characteristic curves of 2SK1338.



Unit: mm



Hitachi Code	TO-3P
JEDEC	—
EIAJ	Conforms
Weight (reference value)	5.0 g

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